

# TECHCON

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## 60TH ANNUAL TECHNICAL CONFERENCE

April 29 - May 4, 2017 | RHODE ISLAND CONVENTION CENTER | PROVIDENCE, RHODE ISLAND

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### General Information

April 29 - May 04, 2017  
Providence, RI

### Self-sputtering initiation in high power impulse magnetron discharge on a hollow-cathodic effect enhanced cylindrical sputtering sources

Tuesday, May 2, 2017: 4:20 PM  
Exhibit Hall (Rhode Island Convention Center)

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Self-sputtering can take place in high power impulse magnetron discharge by a very high power operation because of its high ionization rate of sputtered metal. To obtain self-sputtering more easily, an optimized cylindrical sputtering source based on the hollow-cathodic effect is designed. The discharge process is studied by the plasma global model. When the cylindrical sputtering source is operated by high-power impulse magnetron discharge mode, a higher ionization rate  $\alpha$  and a higher probability of a sputtered and ionized atom return to the target  $\beta$  can be observed because of the hollow cathode effect. The sputtered unionized atoms will repeatedly sputter rather than runaway until ionize to further contribute  $\alpha$  as a result of the physical structure of the cylindrical source. Meanwhile, more ions may collide on the opposite target leading to a much higher  $\beta$  than that induced by low potential only on conventional flat-target. Therefore, a smaller self-sputter yield  $\gamma$  which is positive related with the discharge voltage is needed for the cylindrical source to start self-sputtering.

See more of: [Heureka! Session](#)  
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